



WAH LEE INDUSTRIAL CORP.

華立企業股份有限公司

Material Pioneer, Technology Navigator



INVESTOR MEETING

法說簡報

February 2015

2015年2月

TSE Ticker : 3010 TT

<http://www.wahlee.com>

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合併2013年營運報告

Company Profile 公司簡介

Inception: 10/1/1968

成立日期

Listing: 9/22/2002 on TSE(台灣證券交易所)

掛牌日期

Capital: NT\$ 2,313,901,380

實收資本額

Market Cap: ~USD\$410 million

市值

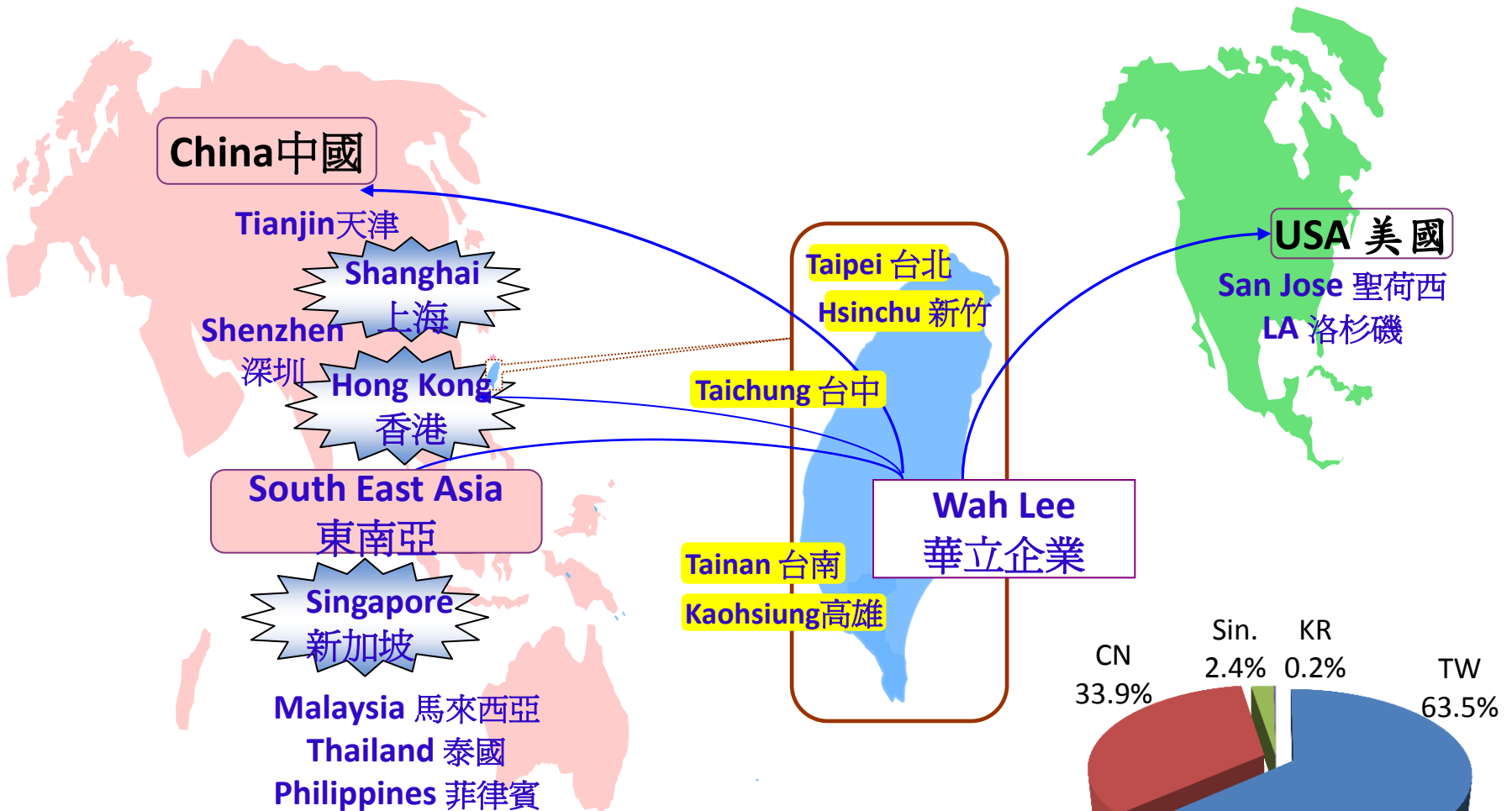
Core Business: Leading HI-TECH solutions integrator and raw

主要業務

materials provider for :

- Computer & Communication 資通訊
- Semiconductor 半導體
- FPD 平面顯示器
- Green Energy/Optoelectronics 綠能/光電

Sales Offices 國際行銷據點



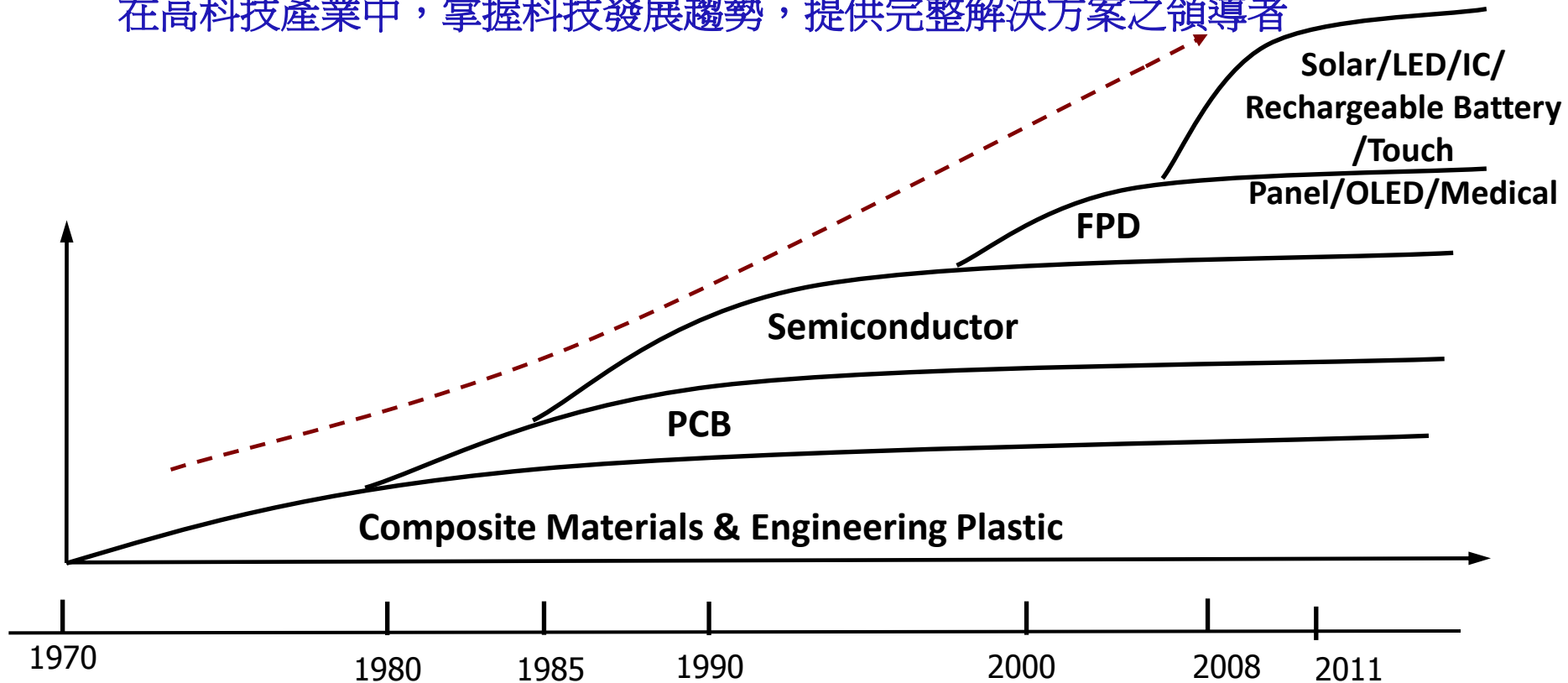
Wah Lee Subsidiaries

2014YTD consolidated sales
合併營收區域別

Wah Lee's Core Competence 華立核心競爭力

- I. Leader in foreseeing technology developments and solutions provider of upstream raw materials & equipment in high-tech industries

在高科技產業中，掌握科技發展趨勢，提供完整解決方案之領導者



II. Developing Next Generation Technologies:

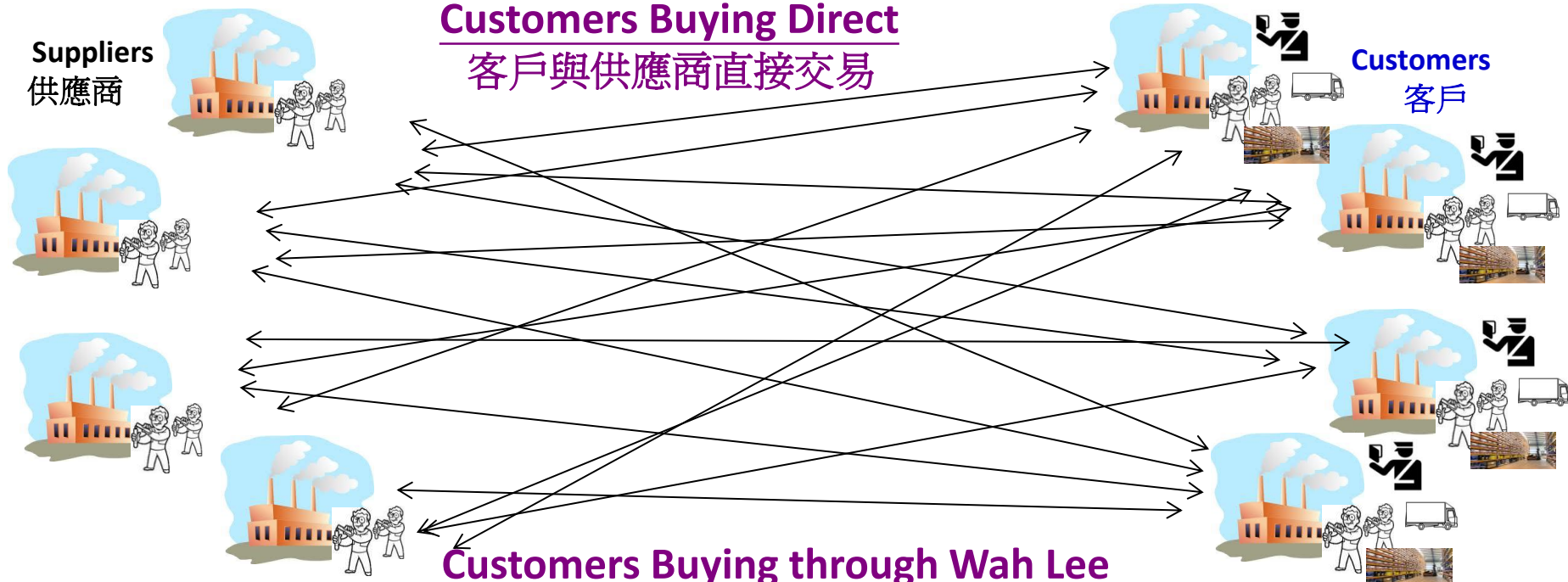
投資開發下一代明星產業，如先進顯示技術，固態照明，太陽能發電，電動車等

- Advanced displays (3D, flexible, transparent...)
- Solid state lighting, advanced solar, electrical vehicle related systems...

Wah Lee's Value Proposition 華立附加價值

Customers Buying Direct

客戶與供應商直接交易



Customers Buying through Wah Lee

華立在供應鏈中提供關鍵附加價值: 一次購足

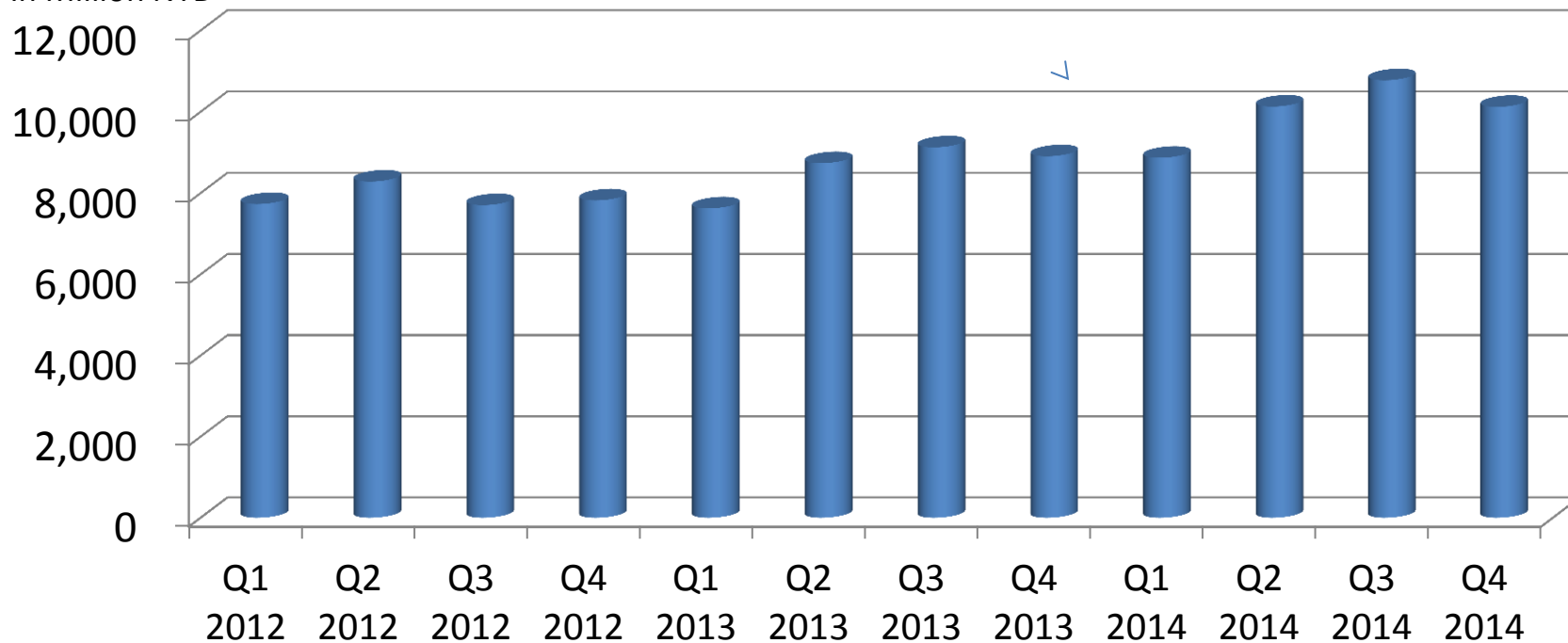


Quarterly Consolidated Sales 季合併營收資訊

季合併營收

Quarterly Consolidated Sales

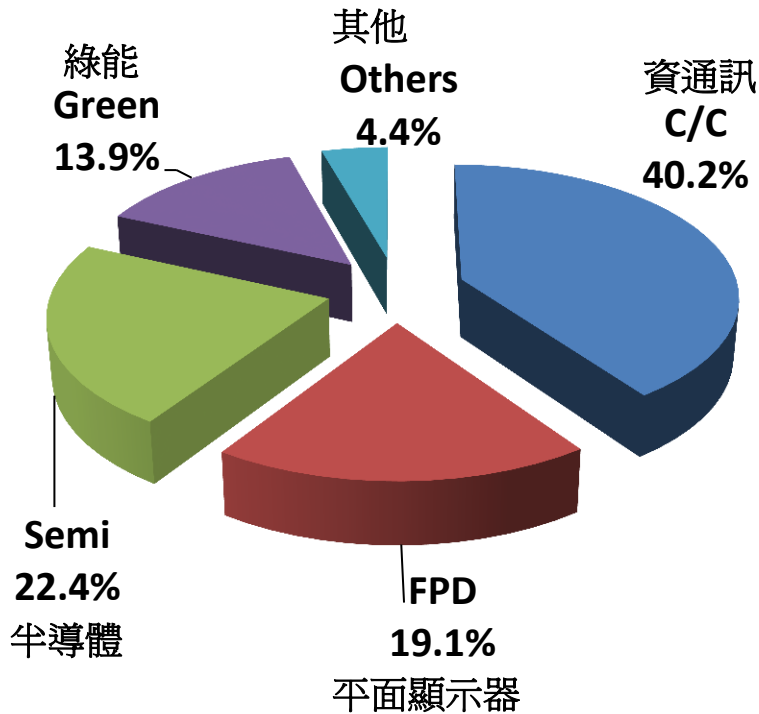
百萬元新台幣
In Million NTD



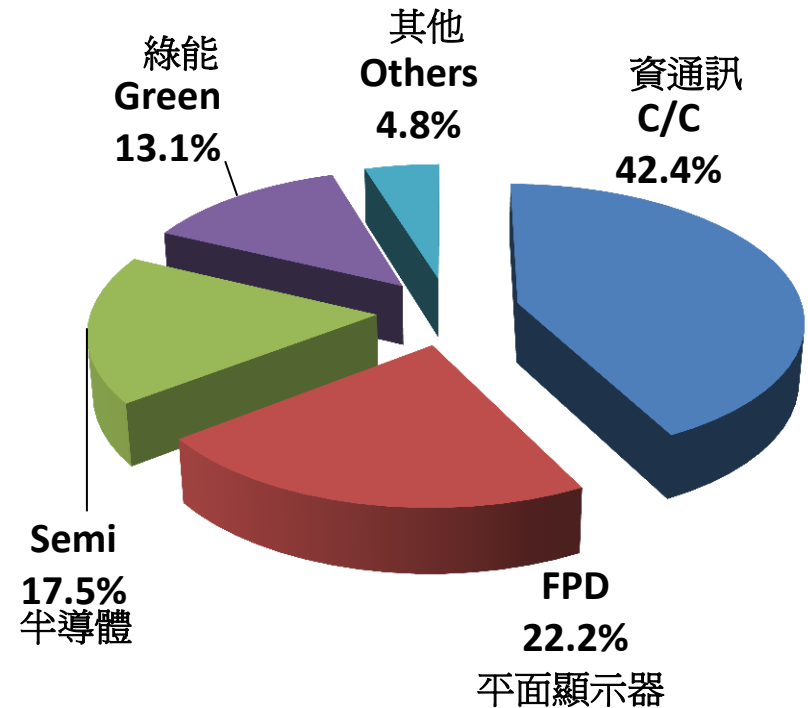
百萬 Mil NTD	2012 Q1	2012 Q2	2012 Q3	2012 Q4	2013 Q1	2013 Q2	2013 Q3	2013 Q4	2014 Q1	2014 Q2	2014 Q3	2014 Q4
Sales	7,732	8,285	7,706	7,822	7,625	8,738	9,127	8,908	8,871	10,130	10,777	10,123
QoQ%	10.3%	7.2%	-7.0%	1.5%	-2.5%	14.6%	4.5%	-2.4%	-0.4%	14.2%	6.4%	-6.1%
YoY%	-10.0%	0.9%	3.9%	11.6%	-1.4%	5.5%	18.5%	13.9%	16.3%	15.9%	18.1%	13.6%

Industry Sales Breakdown 營收產業別資訊

2014/ 01-12



2013/ 01-12



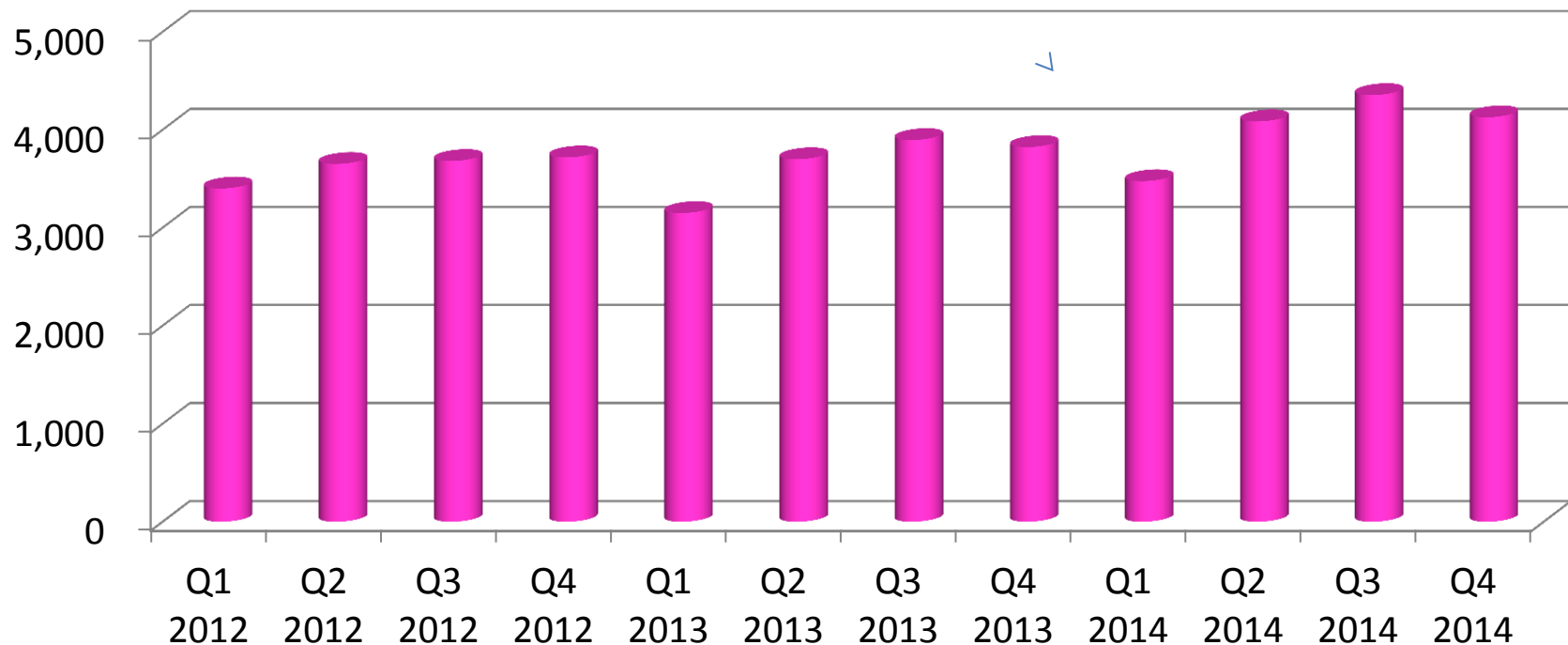
百萬 Mil NTD	C/C	Semi	FPD	Green	Others	Total
2014/ 01-12	16,043	8,916	7,634	5,537	1,771	39,901
2013/ 01-12	14,568	6,041	7,647	4,494	1,648	34,398
YoY%	10.1%	47.6%	-0.2%	23.2%	7.5%	16.0%

Industry Sales Breakdown : C/C 資通訊營收

資通訊用高機能塑膠

Computer Communication Engineering Plastics

百萬元新台幣
In Million NTD

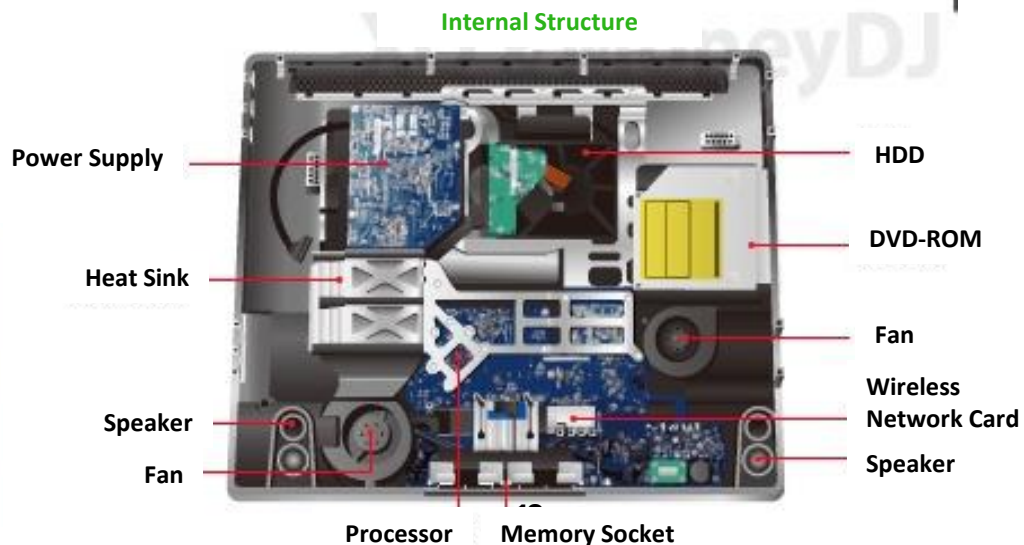
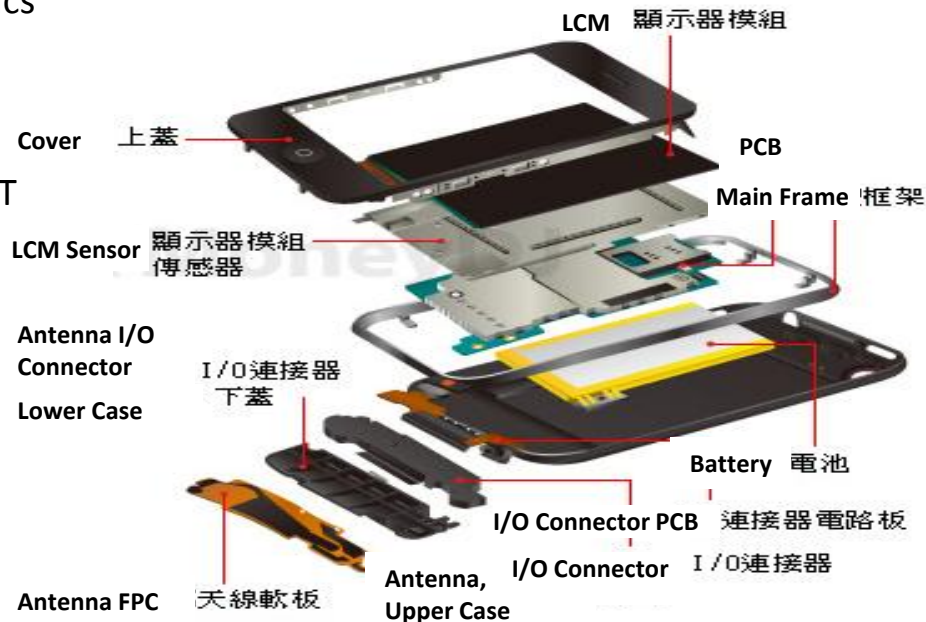


百萬 Mil NTD	2012 Q1	2012 Q2	2012 Q3	2012 Q4	2013 Q1	2013 Q2	2013 Q3	2013 Q4	2014 Q1	2014 Q2	2014 Q3	2014 Q4
Sales	3,401	3,651	3,681	3,718	3,150	3,700	3,895	3,823	3,476	4,086	4,355	4,127
QoQ%	-8.2%	7.4%	0.8%	1.0%	-15.3%	17.4%	5.3%	-1.9%	-9.1%	17.6%	6.6%	-5.2%
YoY%	-17.6%	-14.5%	-4.8%	0.3%	-7.4%	1.3%	5.8%	2.8%	10.3%	10.4%	11.8%	8.0%

Products in C/C 資訊通訊產品

高機能工程塑膠 High Performance Engineering Plastics

1. 外殼 Case : 高機能碳纖 Carbon Fiber、TORAY CFRP、PA
2. 鏡頭 Lens: OKP4、ARTON、HARD COATED SHEET
3. 絕緣片 Insulating Strip、電池 Battery Label : PET FILM、PC FILM、PBT FILM
4. 喇叭 Speaker : PET FILM
5. 充電座 Charge Station : 電木粉 Phenolic Moulding Compound
6. Connector 連接器 : LCP、PA9T
7. Reflector 反射片 : PA9T
8. 變壓器 /PFC : 電木粉 Phenolic Moulding Compound
9. Inverter Bobbin : LCP



高機能工程塑膠近期開發應用領域 1

Recent developments in Engineering Plastics 1



NB、Smart Phone

- Nano Molding Technology (NMT or NMT-like) 開發
- High Stiffness Computer Case 高剛性外殼



車用、3C

- Pulley, Water Pump, Piston, Gasket
- LIB Separator Film 鋰電池隔離膜

高機能工程塑膠近期開發應用領域 2

Recent developments in Engineering Plastics 2



照明 (LED)

- LED Reflector 反射杯



太陽能

- Solar Junction Box 太陽能連接器



民生消費品

- Luggage 行李箱

高機能工程塑膠近期開發應用領域 3

Recent developments in Engineering Plastics 3



3C、家電

- TAFK PE Masking



醫療

- Medical Liquid Bags 醫療輸液袋

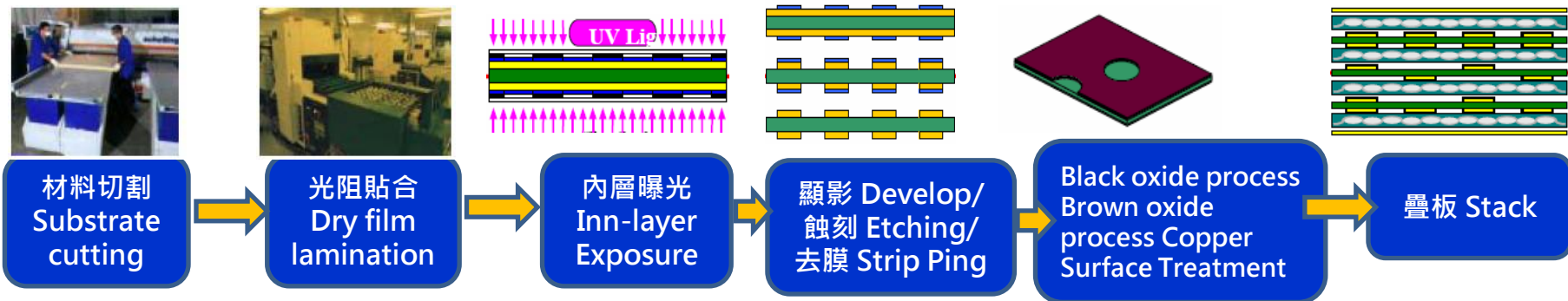


包裝材料、容器

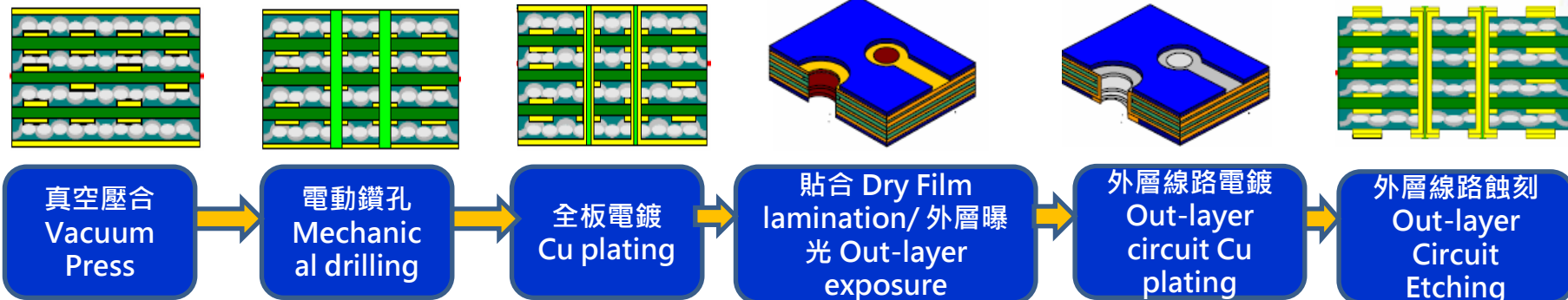
- Food Packaging 食品包裝
- Cosmetics Packaging 化妝品包裝



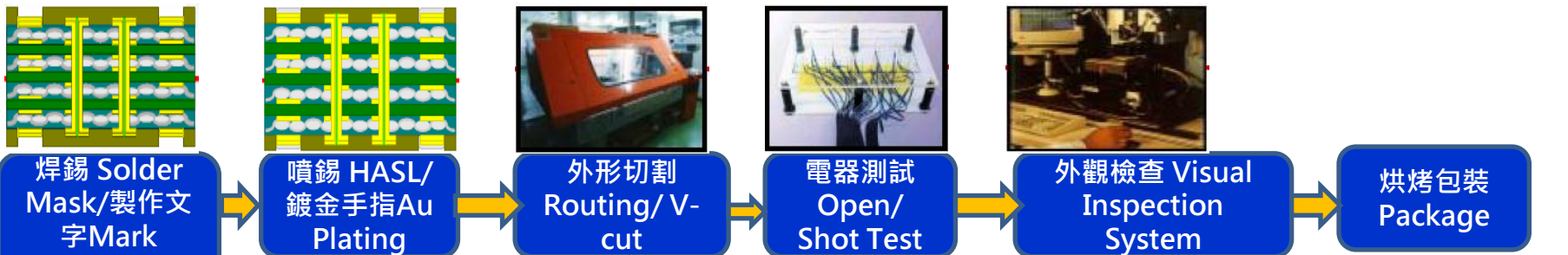
Products in PCB Industry PCB產業產品



- CCL 銅箔基板
- Dry Film 乾膜
- Lamination Machine 軟板貼合機



- Release Film 離型膜
- Dry Film 乾膜



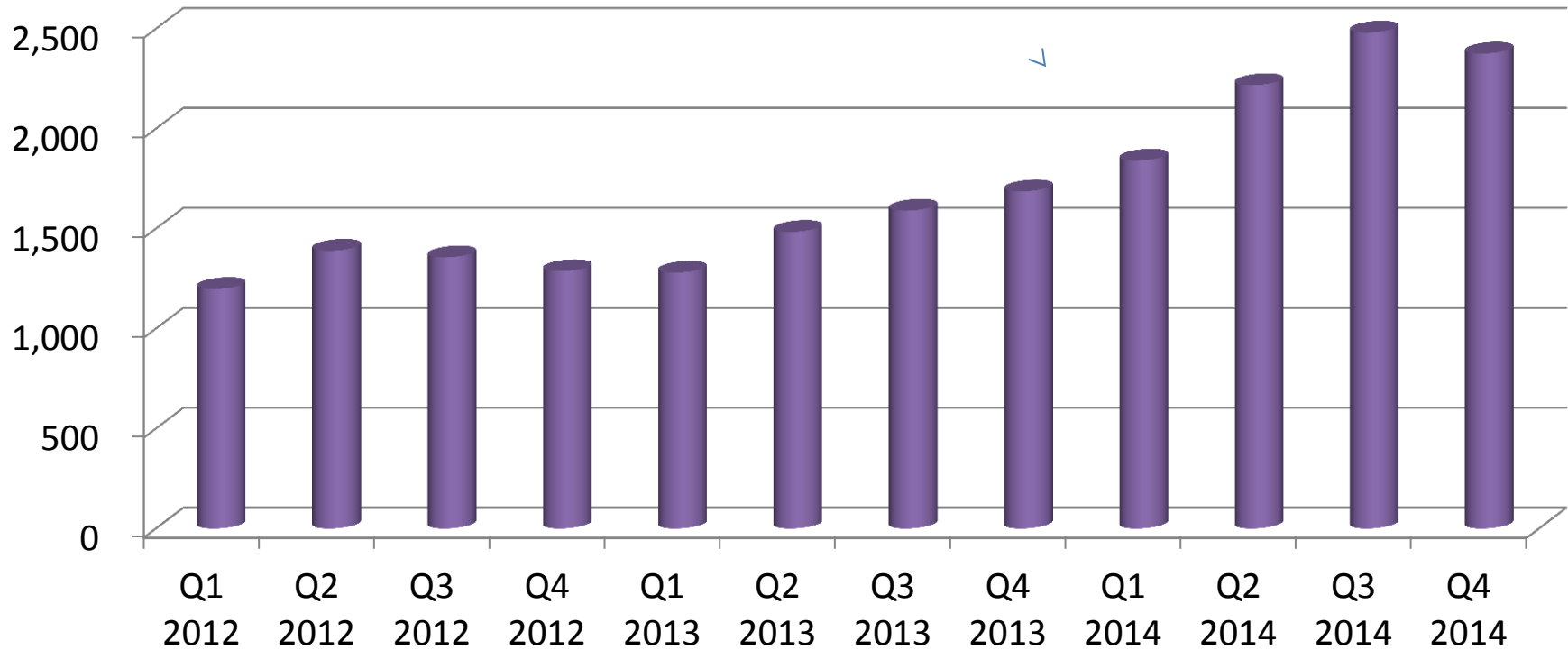
- CNC Router 切割機
- Beveling Machine 磨邊機
- AOI 外觀檢查機
- Screen Visual Inspection 網板檢查機

Industry Sales Breakdown: Semi 半導體營收

半導體產業

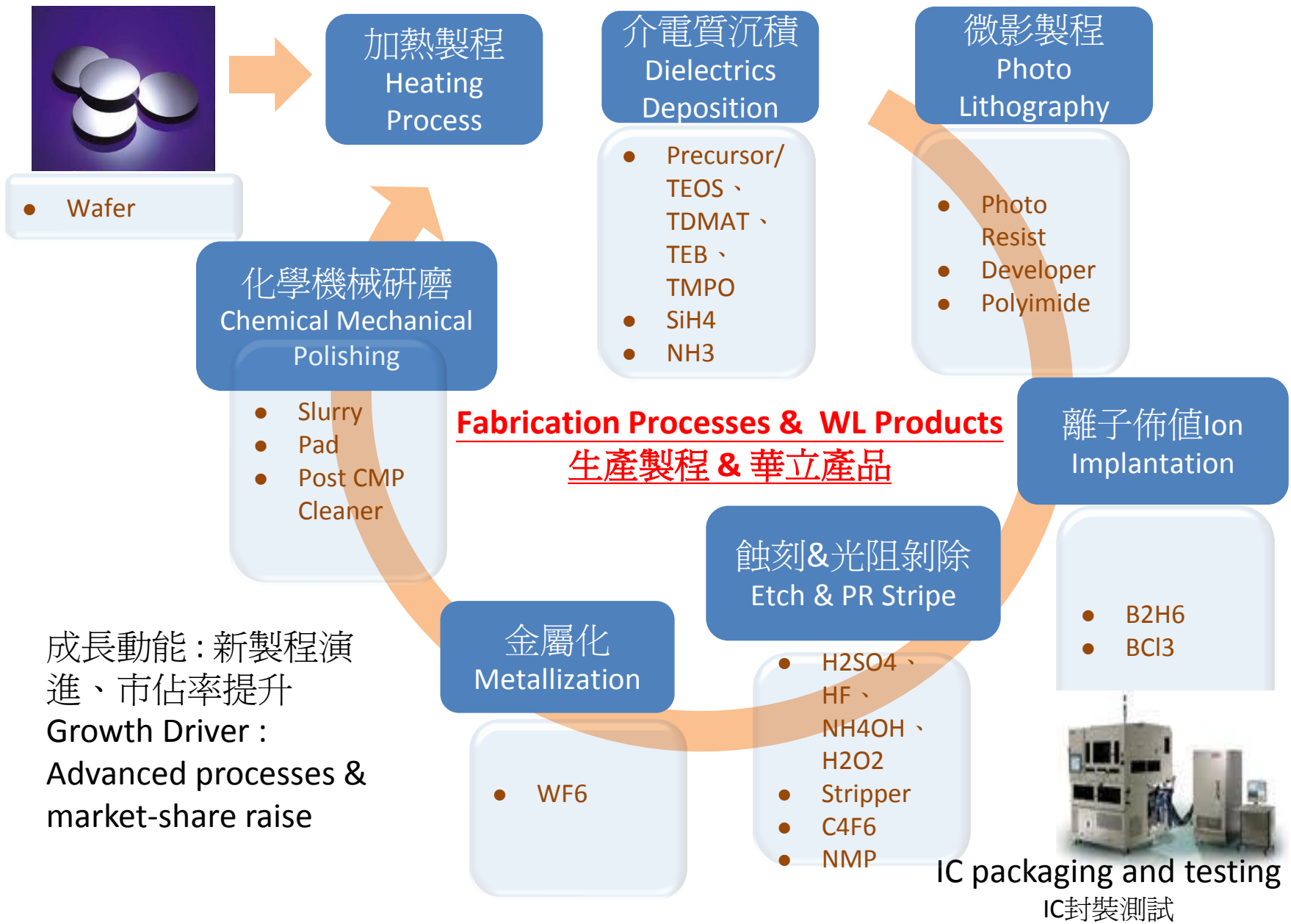
Semiconductor Industry

百萬元新台幣
In Million NTD



百萬 NTD	2012 Q1	2012 Q2	2012 Q3	2012 Q4	2013 Q1	2013 Q2	2013 Q3	2013 Q4	2014 Q1	2014 Q2	2014 Q3	2014 Q4
Sales	1,199	1,390	1,356	1,288	1,280	1,484	1,590	1,687	1,841	2,218	2,481	2,376
QoQ%	-0.6%	15.9%	-2.4%	-5.1%	-0.6%	15.9%	7.2%	6.1%	9.1%	20.5%	11.9%	-4.2%
YoY%	-26.7%	-21.4%	4.4%	6.8%	6.8%	6.8%	17.2%	31.0%	43.8%	49.5%	56.0%	40.9%

Semiconductor Supply Chain 半導體供應鏈

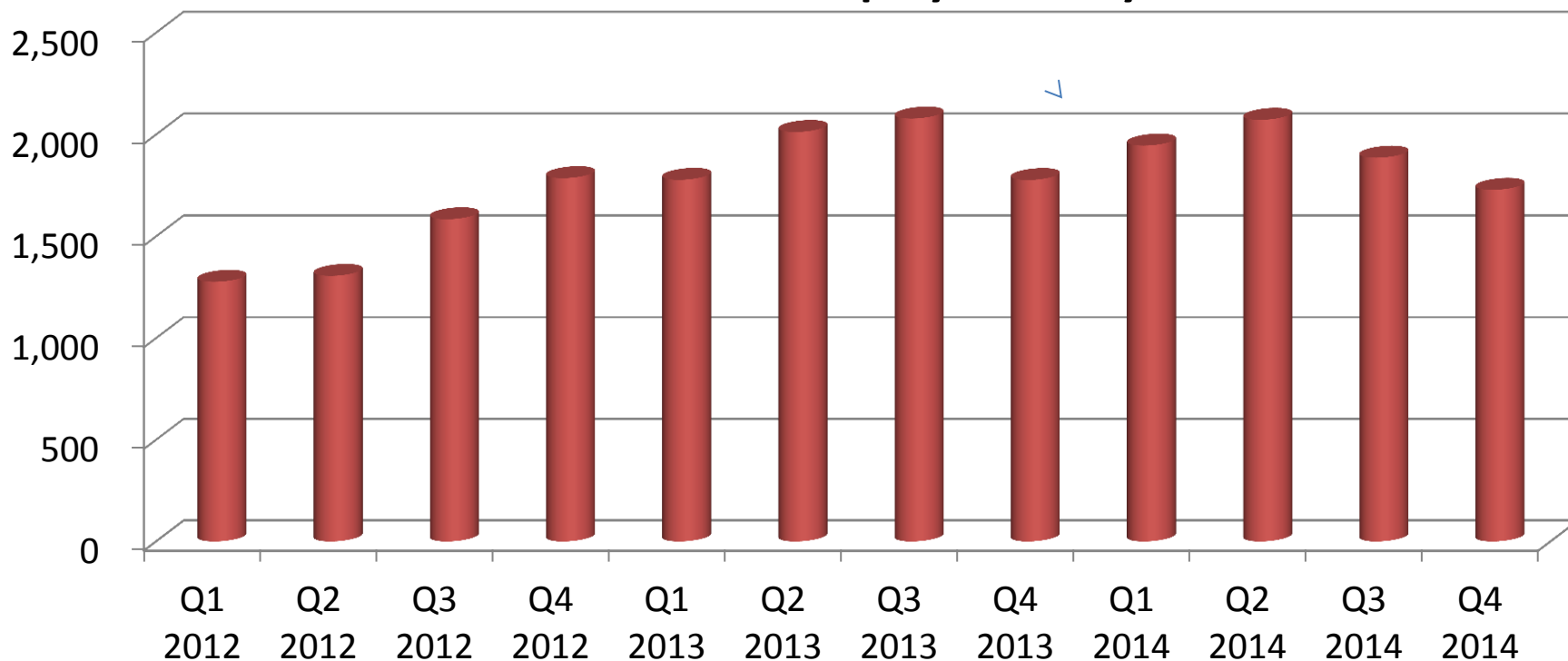


Industry Sales Breakdown: FPD 平面顯示器營收

平面顯示器產業

Flat Panel Display Industry

百萬元新台幣
In Million NTD



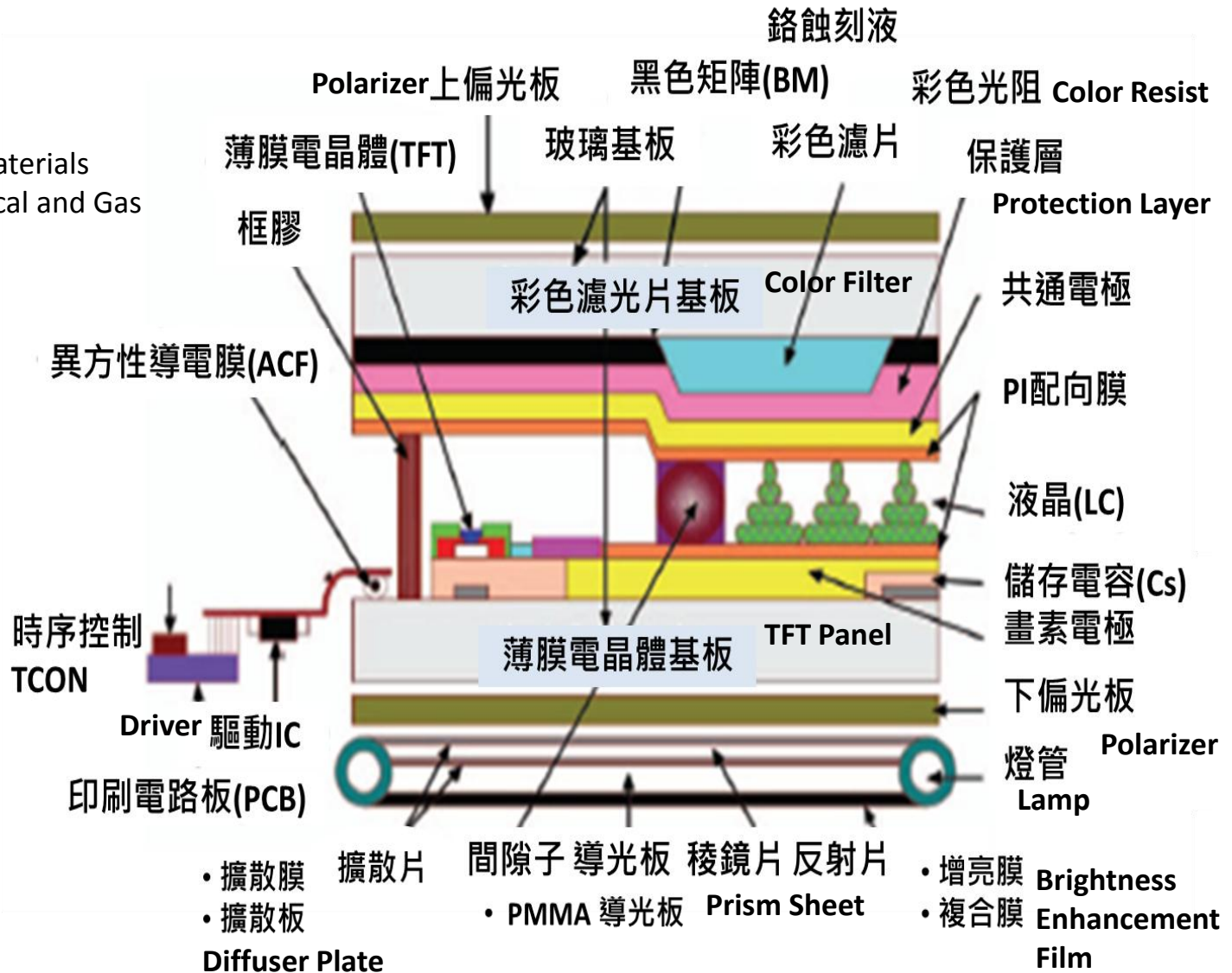
百萬 Mil NTD	2012 Q1	2012 Q2	2012 Q3	2012 Q4	2013 Q1	2013 Q2	2013 Q3	2013 Q4	2014 Q1	2014 Q2	2014 Q3	2014 Q4
Sales	1,277	1,307	1,584	1,786	1,778	2,013	2,079	1,777	1,946	2,072	1,887	1,729
QoQ%	151.6%	2.3%	21.3%	12.7%	-0.5%	13.2%	3.3%	-14.5%	9.5%	6.5%	-9.0%	-8.4%
YoY%	4.8%	110.7%	221.3%	251.9%	39.2%	54.1%	31.2%	-0.5%	9.5%	3.0%	-9.2%	-2.7%

在LCD TV應用中，華立供應超過九成材料 Wah Lee Provides over 90% of Material used in LCD TV

Process Equipment & Materials
Other Processing Chemical and Gas

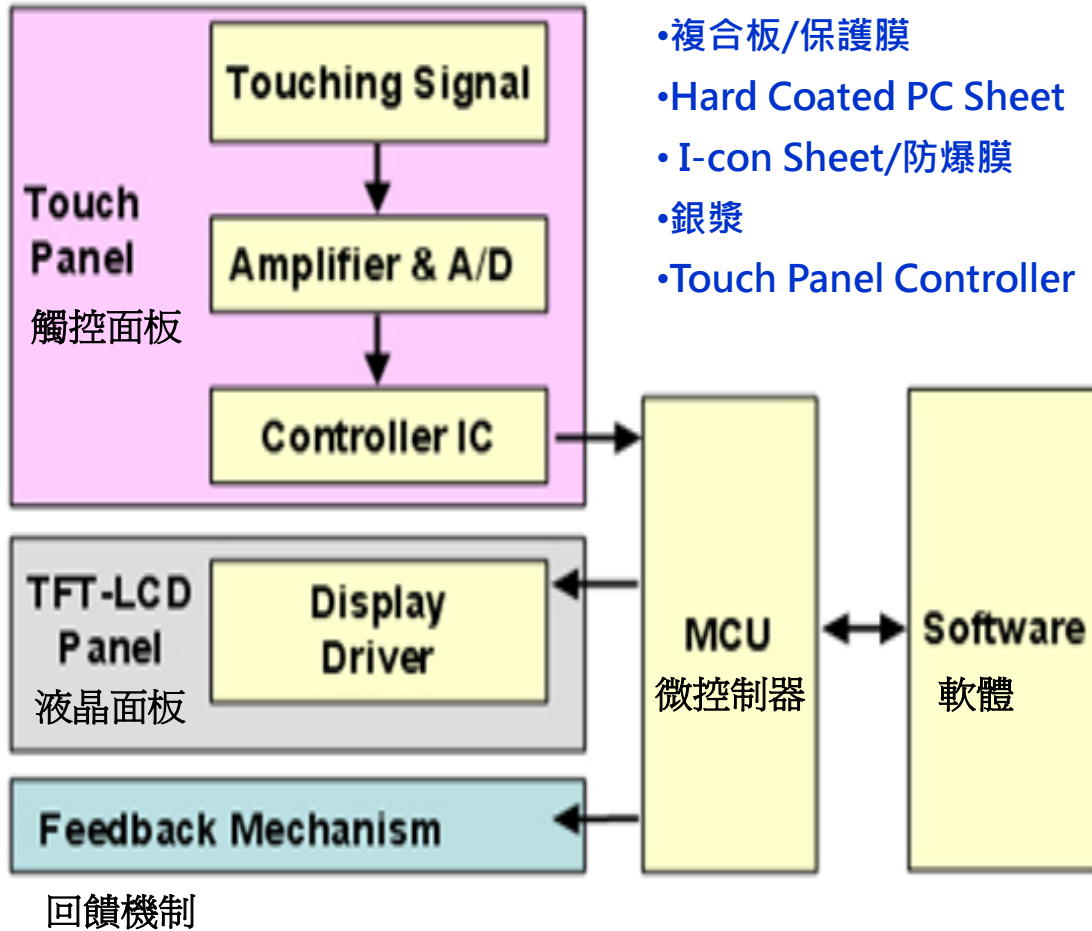
製程設備與耗材
其它製程用化學材
及氣體

- Edge Beam Cleaning : PGME、PGMEA
- Chamber Cleaning : NF3
- 形成 Si 薄膜 : SiH4



在平板與手機應用中，華立提供超過七成材料

Wah Lee Provides over 70% of material used in FPD and Cell Phone



- 複合板/保護膜
- Hard Coated PC Sheet
- I-con Sheet/防爆膜
- 銀漿
- Touch Panel Controller

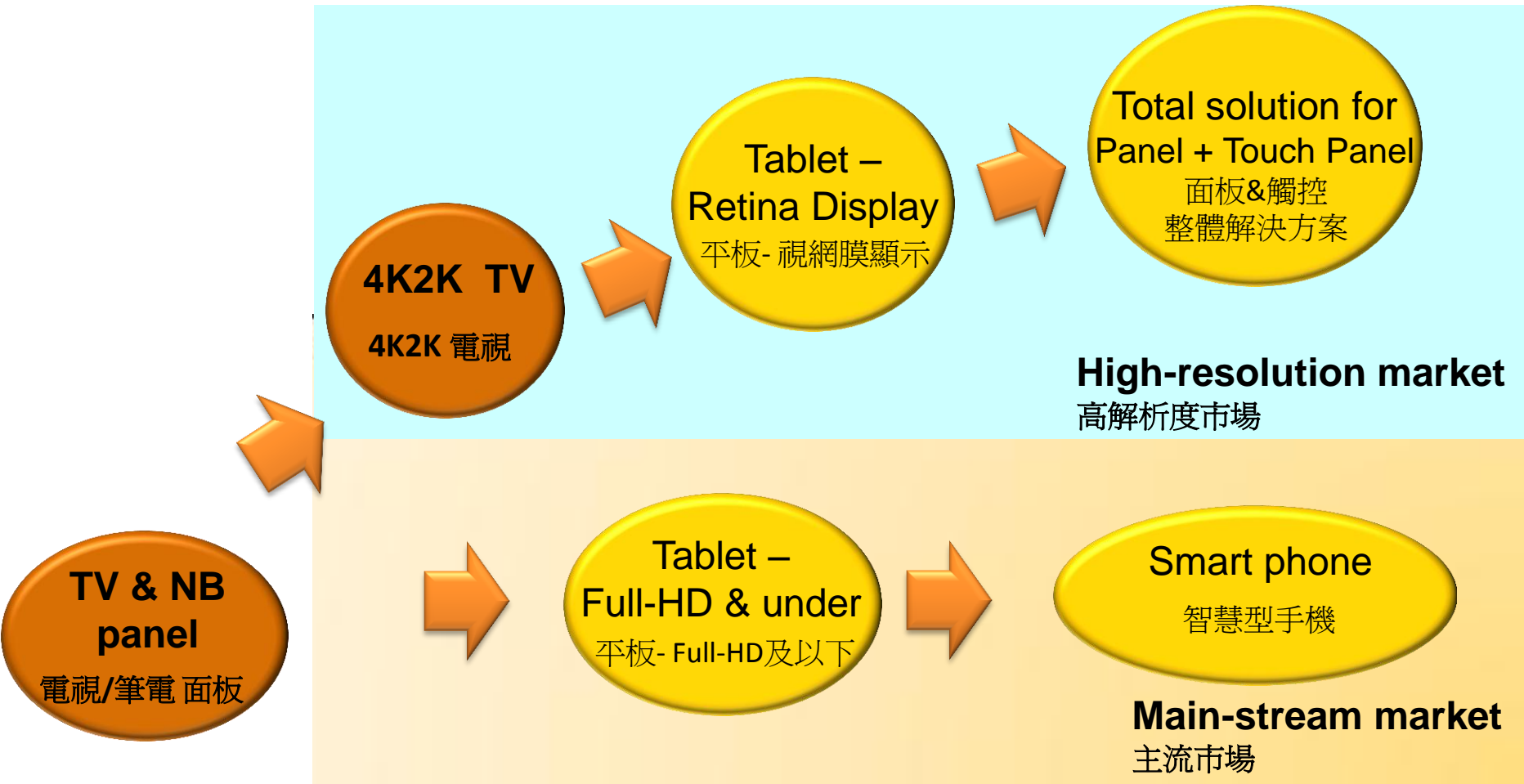


高機能工程塑膠
High performance
Engineering
Plastics、
碳纖維材料
Carbon Fiber...

電池材料
Battery
Materials

PCB/軟板材料
PCB/FBC
Materials

FPD Business Development FPD發展計畫



T-con + power mgt. IC
時序控制+電源管理 IC

Integrated IC (iChip) + Power mgt. IC
整合 IC (iChip) + 電源管理 IC

DisplayPort IC



- NB



- TV



- Smart Phone

Public Information Display (PID) 公共資訊顯示器

- Slim Concept (Narrow Bezel, Slim Depth)
- High Brightness
- Enhanced Durability
- Customize (24"~65" TV set) and Total Solution
- Both Indoor and Outdoor
PID Proposal



Industry Sales Breakdown: Green Energy 綠能營收

綠能產業

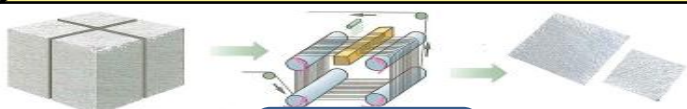
Green Energy Industry

百萬元
In Millions



百萬 Mil NTD	2012 Q1	2012 Q2	2012 Q3	2012 Q4	2013 Q1	2013 Q2	2013 Q3	2013 Q4	2014 Q1	2014 Q2	2014 Q3	2014 Q4
Sales	1,429	1,462	682	542	1,014	1,113	1,160	1,206	1,229	1,360	1,533	1,415
QoQ%	19.6%	2.3%	-53.3%	-20.5%	87.1%	9.7%	4.3%	4.0%	1.9%	10.7%	12.7%	-7.7%
YoY%	52.4%	26.2%	-49.7%	-54.6%	-29.0%	-23.9%	70.1%	122.5%	21.1%	22.2%	32.1%	17.3%

Solar Wafer 矽晶片



矽錠開方

晶片切割

晶片

• 切割鋼線 Wire

- 多晶矽晶片 Poly silicon wafer
- 單晶矽晶片 Single silicon wafer

Solar Cell 電池片



晶片進料檢測

晶片蝕刻清洗

磷擴散

側邊/背面隔離

抗反射層沉積

金屬電極網印

燒結

I-V曲線效率量測與分級

- NF_3 三氟化氮
- IC Chemical 化學液
- Texture etchant 蝕刻液
- POCl_3

- NH_3 氨水
- SiH_4 矽甲烷
- 銀漿、鋁漿 Ag Paste, Al Paste
- 銀/鋁漿 Ag/Al Paste

PV Module 模組



電池選用

焊接與焊串

與EVA、玻璃、Tedlar 組成模組

模組封裝

鋁框、接線盒組裝

效率測試

• Solar Cell 電池片

- Solar Glass 白玻璃
- Back Sheet 背板
- EVA Sheet 材料片

• Junction Box 用PPE

PV System 太陽能系統

小型太陽能系統 System
電廠 Solar Plants



Growth Driver in Solar 太陽能成長動能

- 具彈性的服務模式 Flexible Service Model
 - 除單晶、多晶、銀鋁漿、背板等材料銷售外，進行代工等服務與出海口機會，具備全面產業鏈供應能力 Besides such material sales as silicon wafer/cell/module, Ag/Al paste, back sheet and so on, WL provides a full range of services to the supply chain including OEM and turnkey solutions.
- 海外太陽能電廠營運與開發 Development and Operation of Solar Plants
 - 具備當地市場開發與建置能力 Local market development and EPC (engineering, procurement and construction)
 - 與金融集團合作取得資金槓桿 Cooperation with financial groups for capital leverage

華立全球太陽能電廠開發規劃

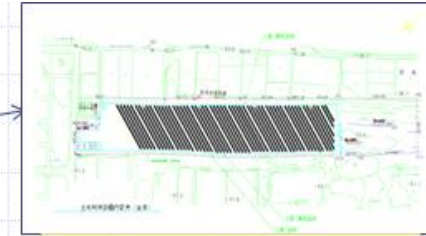


Solar Plants in Japan 日本太陽能電廠建置

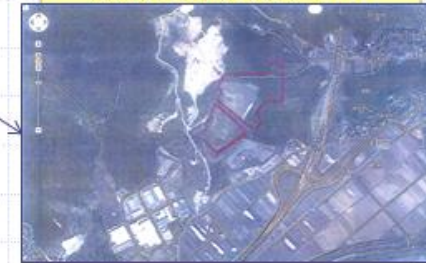
- 搶先把握每度40日圓高收購電價，華立在日本中部地區建置5MW 電廠：Wah Lee established 5 MW solar plants in Japan:
 - 石川縣2MW在2013/08併網售電
Ishikawa Plant (2MW) started generating electricity sales in Aug. 2013 .
 - 富山縣3MW在2014/02併網售電
Toyama Plant (3MW) started generating electricity sales in Feb. 2014.
- 另有超過7MW的日本電廠建置中，華立將持續擴大太陽能出海口的發展，提升供應鏈整體銷售的獲利 More solar plants (over 7MW) are projected to generate electricity sales in Q3 of 2015.



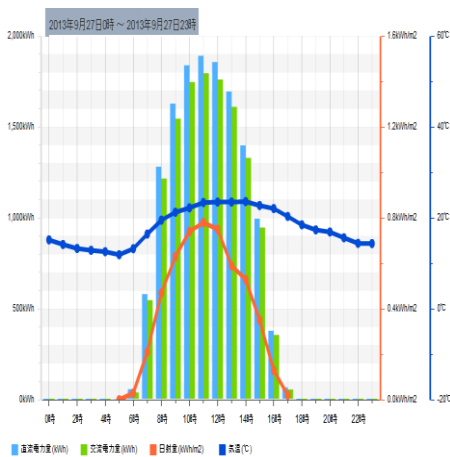
中部地區地圖
案件1-石川縣內灘町
案件2-富山縣高岡市



案件1-石川縣內灘町-2MW



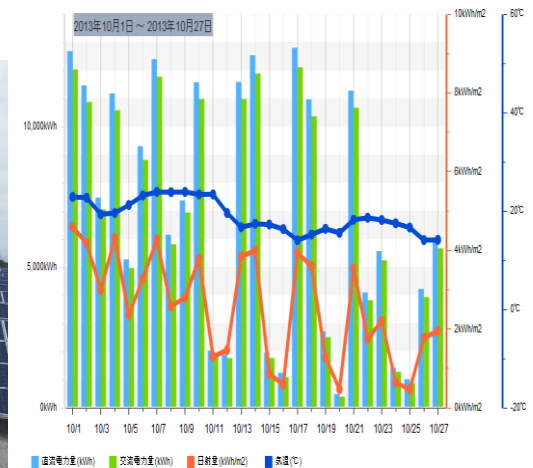
案件2-富山縣高岡市-3MW



2013/9/2 Power Statistics



石川縣2MW地面型電廠
Ishikawa Solar Plant



2013/10 Power Statistics

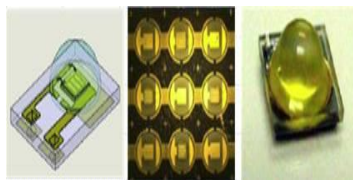
LED Supply Chain

LED產業鏈

1. 原始材料合成
raw materials synthesizing

2. 蒸餾還原形成多晶
distilling/reductive → poly-crystalline

3. 單晶成長單晶棒
single crystal → ingot



saw slicing to be wafer, and surface polishing
將單晶棒鋸切成片狀晶圓，並加以拋光處理。

• 鑽石切割線、PSS

4. 晶圓/基板
wafer/ substrate

• EMITTER

9. 元件/模組
component/module

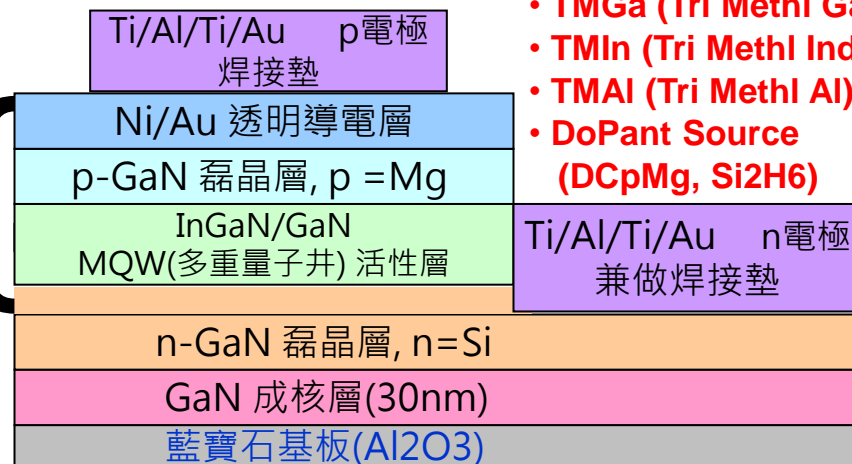
10. 半成品/成品
middle goods / products

• 機構件
• 燈源/燈具



N pole area
N電極
形成區

• AsH₃、PH₃、SiH₄



• NH₃、GaAs
• TMGa (Tri Methl Ga)
• TMIIn (Tri Methl Indium)
• TMAI (Tri Methl Al)
• DoPant Source
(DCpMg, Si₂H₆)

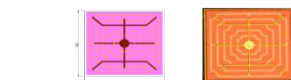
5. 磊晶成長
Epitaxy

6. 晶片製程
(製作電極圖案)
electrode patterning process
• Du Pont EKC Remover

8. 封裝
packaging



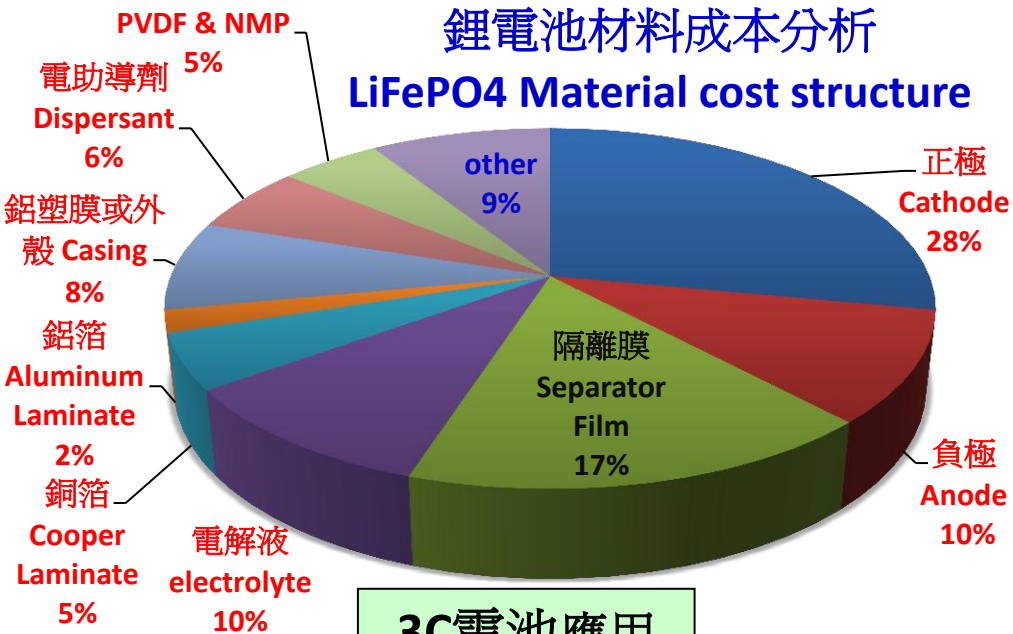
7. 磊晶晶圓減薄
並切割成晶粒
saw slicing to be chips



• PA9T、LCP
• 螢光粉
• 封裝材(矽膠、Hybrid、Epoxy)
• JSR LED Material

Products in Rechargeable Battery 二次電池產品

鋰電池材料成本分析
LiFePO4 Material cost structure



3C電池應用
3C Application



平板 Tablet



智慧型手機
Smart Phone



平板電腦
Tablet PC



無線充電電池系統
Wireless Charging System

動力電池應用
Power Application



電動車
Electric Vehicle



電動機車 E-bike



充電站
Charging Station

電池模組
Module



3C電池芯
Battery Cell



電動車電池模組
Electric Vehicle Module



平板電池模組
Tablet Battery Cell

Biotech Roadmap 生化產業發展規劃



	短期 Short Term (within 1 yr)	中期 Mid Term (within 2 yrs)	長期 Long Term (2 yrs ↑)
製藥 Pharmaceutical	日商/賦形劑 Japan/Excipient		
生化 Biomedical	日商/生化原料 Japan/ Biomedical Material		
	台商/生化原料 Taiwan/ Biomedical Material (談代理權中)		
	台商/飼料用生化原料 Taiwan/ Biotech Material (已投資&取得銷售權)		
醫材 Medical Tools/ Equipment	日商/塑膠原料&膠材 Plastic Materials in China		
	台商/一,二級醫材 – Medical Related Material		
	日商/手術器材 Japan/ Surgery Tools 台商&日商/醫療服務醫材(大陸Project)in China		
保健食品 Dietary Supplements	台商/保健食品 Taiwan		
	日商/原料,保健食品(評估代理) Japan		

2014 Q1-Q3 Consolidated Income Statement

2014 前三季合併損益表

Unit: NT\$ million	2014 前三季 (CPA)	2013前三季 (CPA)	YoY	2014 to Q3 as % of Full 2013
Net Sales 營收淨額	29,778.2	25,490.6	16.8%	86.6%
Gross Profit 銷貨毛利	2,645.1	2,295.9	15.2%	85.2%
Gross Margin 毛利率	8.9%	9.0%	-0.1%	
Op. Expense 營業費用	1,728.9	1,529.8	13.0%	82.9%
Op. Profit 營業利益	916.2	766.1	19.6%	89.9%
Non-op. Profit 業外收支	373.4	447.0	-16.5%	60.2%
L-T investment income 長投收益	237.3	269.0	-11.8%	77.9%
Disposal gain 處分利益	93.0	8.1	1048.0%	116.6%
Others 其他	43.1	169.9	-74.6%	18.3%
Pre-tax Profit 稅前利潤	1,289.6	1,213.1	6.3%	78.7%
Net Income 稅後淨利	988.2	919.6	7.5%	79.8%
After tax EPS	4.01	3.71	7.5%	80.0%

* Consolidated entities include: Wah Lee Taiwan and China Subsidiaries (Raycong, Shanghai YiKang), Skypower (Japan), Wah Lee Tech (Singapore), and Wah Lee Korea.

* 上述合併報表主體，包含華立台灣、大陸子公司(華港香港、上海怡康)、日本Skypower、華立新加坡，及華立韓國。 29

2014 Q1-Q3 Long Term Investments 長期投資收益

Unit: NT\$ thousand

Long-term Investments 轉投資事業	Product Lines 主要產品線	Holding % 持有比例 %	2014Q1-Q3 Earnings Recognized 長投收益
Chang Wah Electromaterials Inc. 長華電材	Semiconductor Packaging and Testing Materials	28	81,126
Nagase Wah Lee Plastics 長華塑膠	SABIC Engineering Plastics	40	92,269
Wah Hong Industrial Corp. 華宏新技	Optical Film, High Performance Plastic Compound, Heat Dissipation Solution, VCM Actuator	26	56,938
ORC Wah Lee Technology Corp. 華展光電	ORC Exposure Machine and Lamps	35	7,016
Total			237,349

2014Q3 Consolidated Balance Sheet 合併資產負債表

Unit: NT\$ million

	2014-09-30 (CPA)		2013-09-30 (CPA)			2014-09-30 (CPA)		2013-09-30 (CPA)	
Cash & Equiv. 現金	2,522	9.6%	2,081	9.4%	S-T Borrowing 短期借款	5,480	20.8%	4,012	18.0%
A/R 應收帳款	11,502	43.8%	9,728	43.7%	A/P 應付帳款	7,393	28.1%	6,124	27.5%
Inventory 存貨	3,438	13.1%	2,792	12.5%	Other C/L 其他流動負債	387	1.5%	282	1.3%
Other C/A 其他流動資產	2,090	8.0%	1,605	7.2%	Current Liab. 流動負債	13,260	50.4%	10,418	46.8%
Current Assets 流動資產	19,552	74.4%	16,206	72.8%	L-T Borrowing 長期借款	1,174	4.5%	1,687	7.6%
Financial Asset-Non Current 金融資產-非流動	527	2%	473	2.1%	Other Liab. 其他負債	1,929	7.3%	841	3.8%
L-T investments 長期投資	4,096	15.6%	3,866	17.4%	Non-Current Liab. 非流動負債	3,103	11.8%	2,528	11.4%
Fixed Assets 固定資產	1,592	6.1%	1,270	5.7%	Total Liab. 總負債	16,363	62.2%	12,946	58.2%
Other Assets 其他資產	519	2.0%	439	2.0%	Capital 股本	2,314	8.8%	2,314	10.4%
Non-Current Asset 非流動資產	6,734	25.6%	6,048	27.2%	Capital Surplus 資本公積	1,304	5.0%	1,263	5.7%
					Retained Earnings 保留盈餘	5,262	20.0%	4,720	21.2%
					Other Equities 其他權益	269	1.0%	329	1.5%
					Non-Controlling. Interest 非控制權益	774	2.9%	682	3.1%
Total Assets 總資產	26,286	100.0%	22,254	100.0%	Total Equities 總股東權益	9,923	37.8%	9,308	41.8%

* Consolidated entities include: Wah Lee Taiwan and China Subsidiaries (Raycong, Shanghai YiKang), Skypower (Japan), Wah Lee Tech (Singapore), and Wah Lee Korea.

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Consolidated Financial Indicators 合併財務比率

	2007	2008	2009	2010	2011	2012	2013	2014Q3
Current Ratio 流動比率	144.8%	148.6%	171.7%	162.6%	164.4%	162.2%	158.2%	147.5%
Quick Ratio 速動比率	98.8%	95.6%	132.4%	115.9%	122.2%	130.9%	127.7%	117.5%
Net Debt/Equity 淨負債比率	36.2%	42.3%	9.0%	22.3%	31.0%	20.7%	17.4%	38.5%
A/R days 應收帳款天數	84.8	86.3	102.1	87.9	88.9	95.2	96.2	97.1
Inventory days 存貨天數	53.4	64.8	69.6	47.6	46.2	40.7	35.6	34.9
A/P days 應付帳款天數	57.9	54.2	62.7	61.2	56.8	58.9	62.0	61.1
Cash conversion days 現金週轉天數	80.3	96.9	108.9	74.4	78.2	76.9	69.8	70.8
Operating cash flow (NT\$K) 來自營業活動現金流量	243,444	636,700	2,539,747	-389,836	603,661	1,444,741	855,991	-838,222
ROE 股東權益報酬率	18.7%	12.0%	12.3%	19.7%	12.7%	12.5%	13.5%	13.5%

* ROE of 2014Q3 is annualized.

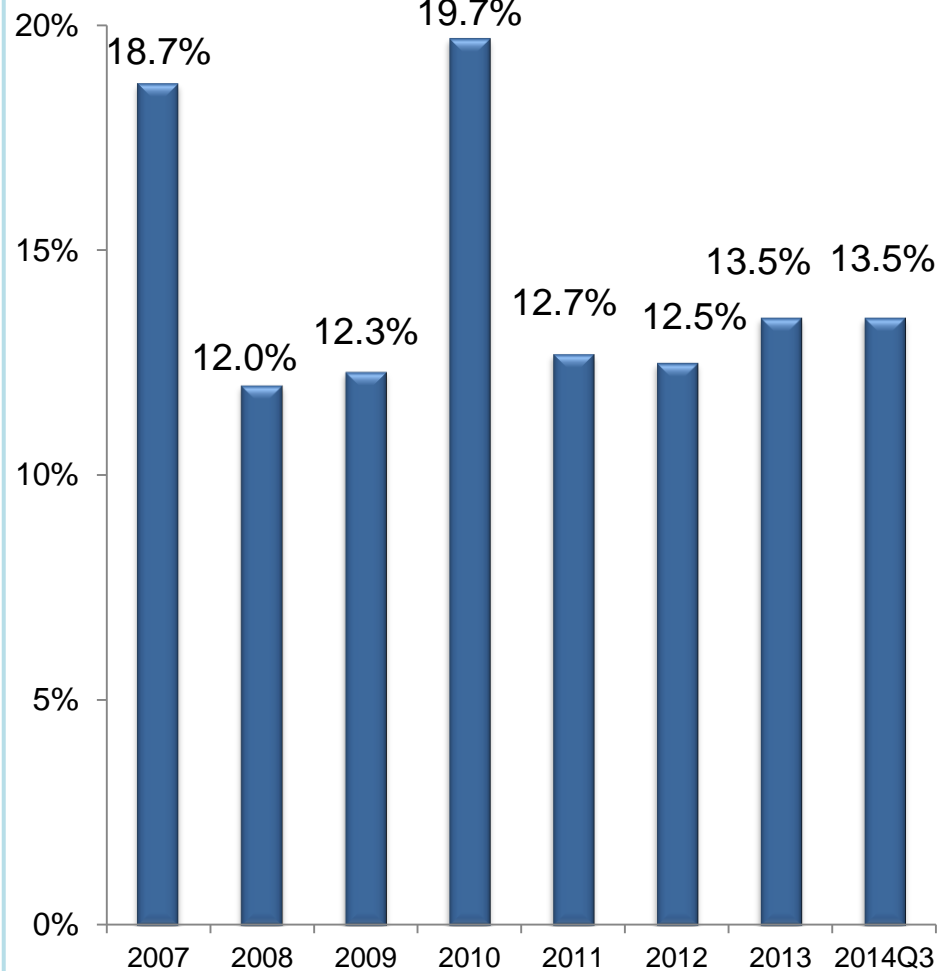
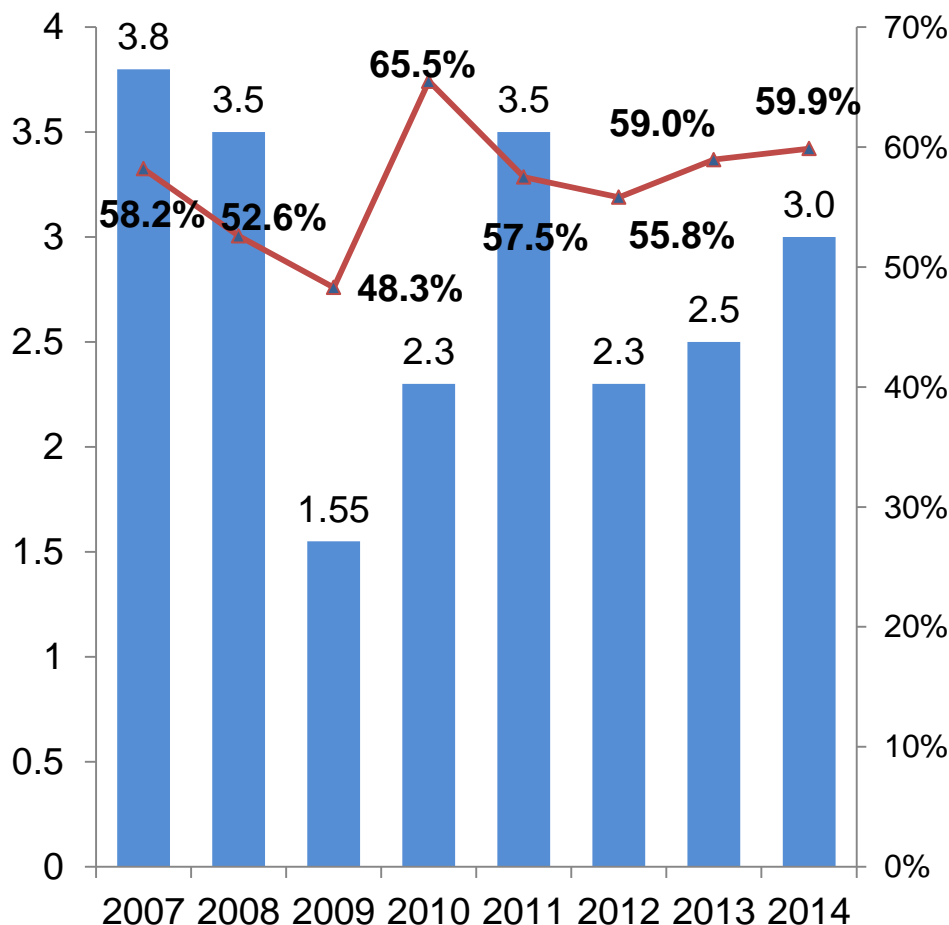
Shareholder Returns Trend 股東投資報酬

Dividend Policy 股利政策

ROE 股東權益報酬率

Cash Dividend
現金股息 (NT\$)

Payout Ratio
現金股息發放比率



* Dividends are distribution of prior year's earnings.

*上述股利乃分派前一年度之盈餘

* ROE of 2014Q3 is annualized.

* 2014 Q3 ROE 經年化處理

2013 Consolidated Income Statement 合併損益表

Unit: NT\$ million	2013 (CPA)	2012 (CPA)	YoY
Net Sales 營收淨額	34,398.4	31,545.3	9%
Gross Profit 銷貨毛利	3,104.1	2,857.9	9%
Gross Margin 毛利率	9.0%	9.1%	0.0%
Op. Expense 營業費用	2,085.4	2,014.3	4%
Op. Profit 營業利益	1,018.8	843.6	21%
Non-op. Profit 業外收支	620.0	479.6	29%
L-T investment income 長投收益	304.8	415.7	-27%
Disposal gain 處分利益	79.7	4.1	1845%
Others 其他	235.5	59.8	294%
Pre-tax Profit 稅前利潤	1,638.8	1,323.2	24%
Net Income 稅後淨利	1,159.5	987.8	17%
After tax EPS	5.01	4.27	17%

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2013 Long Term Investments 長期投資收益

Unit: NT\$ thousand

Long-term Investments 轉投資事業	Product Lines 主要產品線	Holding % 持有比例 %	2013 Earnings Recognized 長投收益
Chang Wah Electromaterials Inc. 長華電材	Semiconductor Packaging and Testing Materials	28	138,430
Nagase Wah Lee Plastics 長華塑膠	SABIC Engineering Plastics	40	128,508
Wah Hong Industrial Corp. 華宏新技	Optical Film, High Performance Plastic Compound, Heat Dissipation Solution, VCM Actuator	26	23,529
ORC Wah Lee Technology Corp. 華展光電	ORC Exposure Machine and Lamps	35	14,295
Total			304,762

2013 Consolidated Balance Sheet 合併資產負債表

Unit: NT\$ million

	2013-12-31 (CPA)		2012-12-31 (CPA)			2013-12-31 (CPA)		2012-12-31 (CPA)	
Cash & Equiv. 現金	3,339	14.4%	1,739	8.5%	S-T Borrowing 短期借款	4,143	17.9%	3,632	17.8%
A/R 應收帳款	9,514	41.1%	8,614	42.3%	A/P 應付帳款	6,386	27.6%	5,470	26.9%
Inventory 存貨	3,081	13.3%	2,650	13.0%	Other C/L 其他流動負債	264	1.1%	191	0.9%
Other C/A 其他流動資產	1,140	4.9%	1,929	9.5%	Current Liab. 流動負債	10,793	46.7%	9,293	45.6%
Current Assets 流動資產	17,074	73.8%	14,931	73.3%	L-T Liab. 長期負債	1,800	7.8%	1,561	7.7%
Financial Asset-Non Current 金融資產-非流動	245	1%	546	2.7%	Other Liab. 其他負債	878	3.8%	764	3.8%
L-T investments 長期投資	4,008	17.3%	3,511	17.2%	Non-Current Liab. 非流動負債	2,678	11.6%	2,326	11.4%
Fixed Assets 固定資產	1,344	5.8%	1,009	5.0%	Total Liab. 總負債	13,471	58.2%	11,618	57.0%
Other Assets 其他資產	456	2.0%	370	1.8%	Capital 股本	2,314	10.0%	2,314	11.4%
Non-Current Asset 非流動資產	6,053	26.2%	5,435	26.7%	Capital Surplus 資本公積	1,260	5.4%	1,246	6.1%
					Retained Earnings 保留盈餘	5,029	21.7%	4,439	21.8%
					Other Equities 其他權益	343	1.5%	174	0.9%
					Non-Controlling. Interest 非控制權益	710	3.1%	575	2.8%
Total Assets 總資產	23,127	100.0%	20,366	100.0%	Total Equities 總股東權益	9,656	41.8%	8,748	43.0%

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